



# BAW56

Rev.E May.-2021

DATA SHEET

## / Descriptions

Silicon Diode in a SOT-23 Plastic Package.

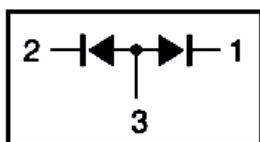
## / Features

Small package, double diode, high switching speed, high repetitive peak reverse voltage, repetitive peak forward current up to 450mA. HF Product.

## / Applications

High-speed switching in thick and thin-film circuits..

## / Equivalent Circuit



## / Pinning



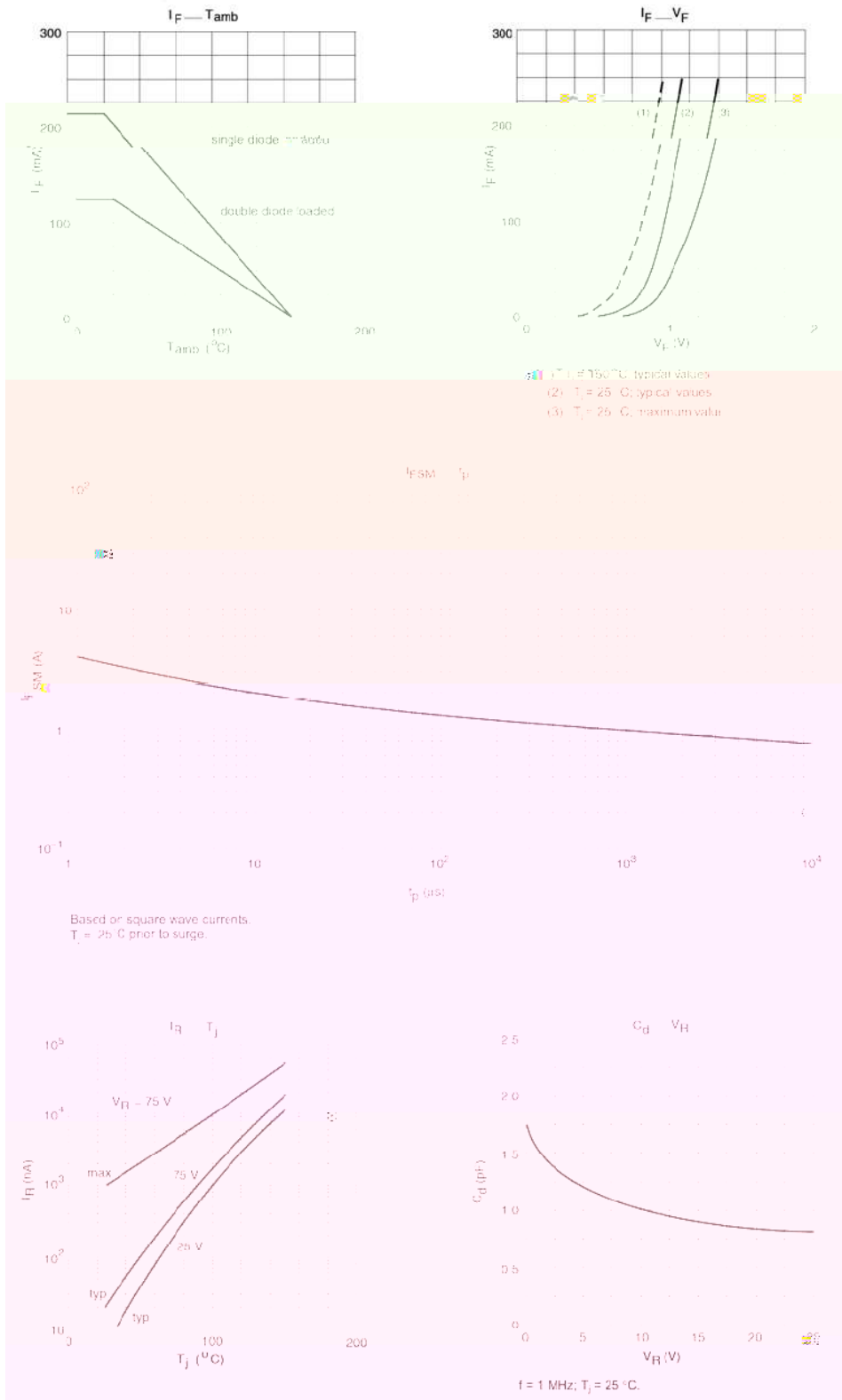
PIN: See Equivalent Circuit.

## / hFE Classifications & Marking

Marking	HA1
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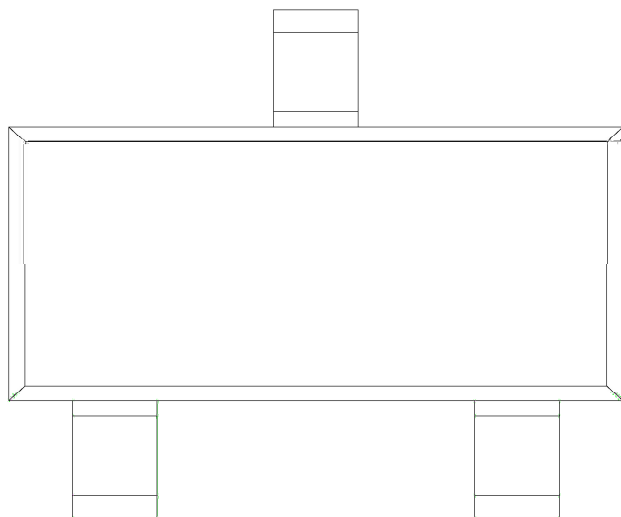
Parameter	Symbol	Rating	Unit
Repetitive Reverse Voltage	$V_{RRM}$	85	V
Continuous Reverse Voltage	$V_R$	75	V
Average Rectified Forward Current	$I_{F(\text{single diode loaded})}$	215	mA
	$I_{F(\text{double diode loaded})}$	125	mA
Repetitive Peak Forward Current	$I_{FRM}$	450	mA
Non-repetitive Peak Forward Surge Current	$I_{FSM(1)(t=1\mu S)}$	4.0	A
	$I_{FSM(2)(t=1mS)}$	1.0	A
	$I_{FSM(3)(t=1S)}$	0.5	A
Power Dissipation Junctioc	$P_{tot}$	250	mW

**/ Electrical Characteristic Curve**



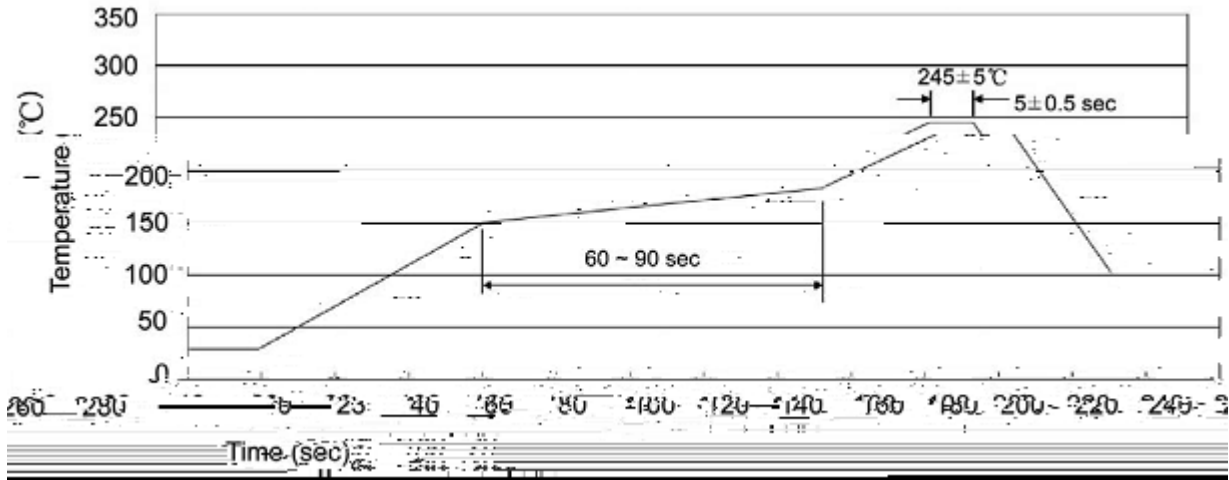


**/ Marking Instructions**



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( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |     |     |    |          |   |
|---|-----|-----|----|----------|---|
| 1 | 25  | 150 | 60 | 90sec;   | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245 | 5   | 5  | 0.5sec;  | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 |     |     | 2  | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260 5                      10 1 sec.                      Temp.:260±5°C                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )	
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱	盒	箱